

AMENDMENTS

Please enter the following amendments:

In the Claims

Please amend the claims as indicated below. The language being added is underlined (“ ”) and the language being deleted contains strikethrough (“”):

1. (Original) A method for forming a package for an electrical device, said method comprising the steps of:
 - attaching a removable material to a surface of a conductive material;
 - forming isolated conductive features within said conductive material;
 - attaching encapsulant to said isolated conductive features and said removable material; and
 - removing said removable material from said conductive features and said encapsulant.
2. (Original) The method for forming a package for the electronic device of claim 1, wherein said forming step includes patterning a surface of said conductive material with a material resistant to an etchant and etching said conductive material with said etchant.
3. (Original) The method for forming a package for the electronic device of claim 1, further comprising the step of forming a die attach pad within said conductive material.
4. (Original) The method for forming a package for the electronic device of claim 1, further comprising the step of coupling the device to said die attach pad.

5. (Original) The method for forming a package for an electronic device of claim 1, further comprising the step of electrically coupling an input/output portion of the device to said isolated conductive feature.

6. (Original) The method for forming a package for the electronic device of claim 1, further comprising the step of singulating individual packaged devices.

7. (Original) The method of claim 1, wherein the removable material is water soluble adhesive.

8. (Original) The method of claim 7, wherein the removable material is removed with deionized water.

9-15. (Canceled)